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67,200-409; TSMC 00-661
Serial Number 09/978,420

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TO: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

FROM: Tung & Associates
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Bloomfield Hills, MI 48302

DATE: 28 April 2004

REF: Appellant : Chen et al Filing Date : 15 October 2001
Serial No. : 09/978,420 Att'y No. : 67,200-409; TSMC 00-661
Art Unit : 2815 Examiner : N. Drew Richards
Title : Microelectronic Fabrication With Upper Lying Aluminum Fuse
Layer in Copper Interconnect Semiconductor Technology and
Method for Fabrication Thereof

AMENDMENT AND RESPONSE TO OFFICE ACTION

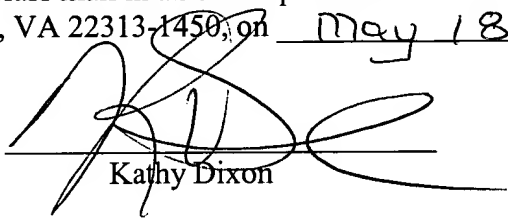
Sir:

In response to an office action mailed on 24 March 2004, please consider the following amendments and remarks pertaining to the above referenced application.

There are no amendments to the specification. Amendments to the claims are found within a Listing of the Claims that begins on page 2 of this paper. There are no amendments to the drawings. Remarks begin on page 4 of this paper.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, POB 1450, Alexandria, VA 22313-1450, on May 18 2004.


Kathy Dixon